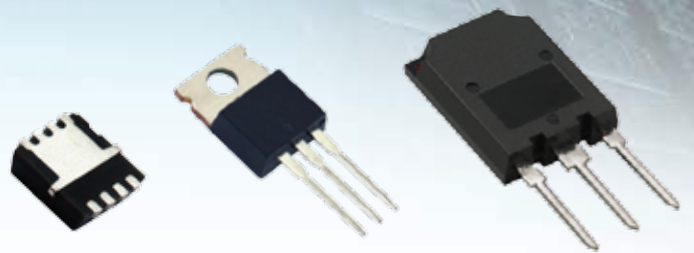
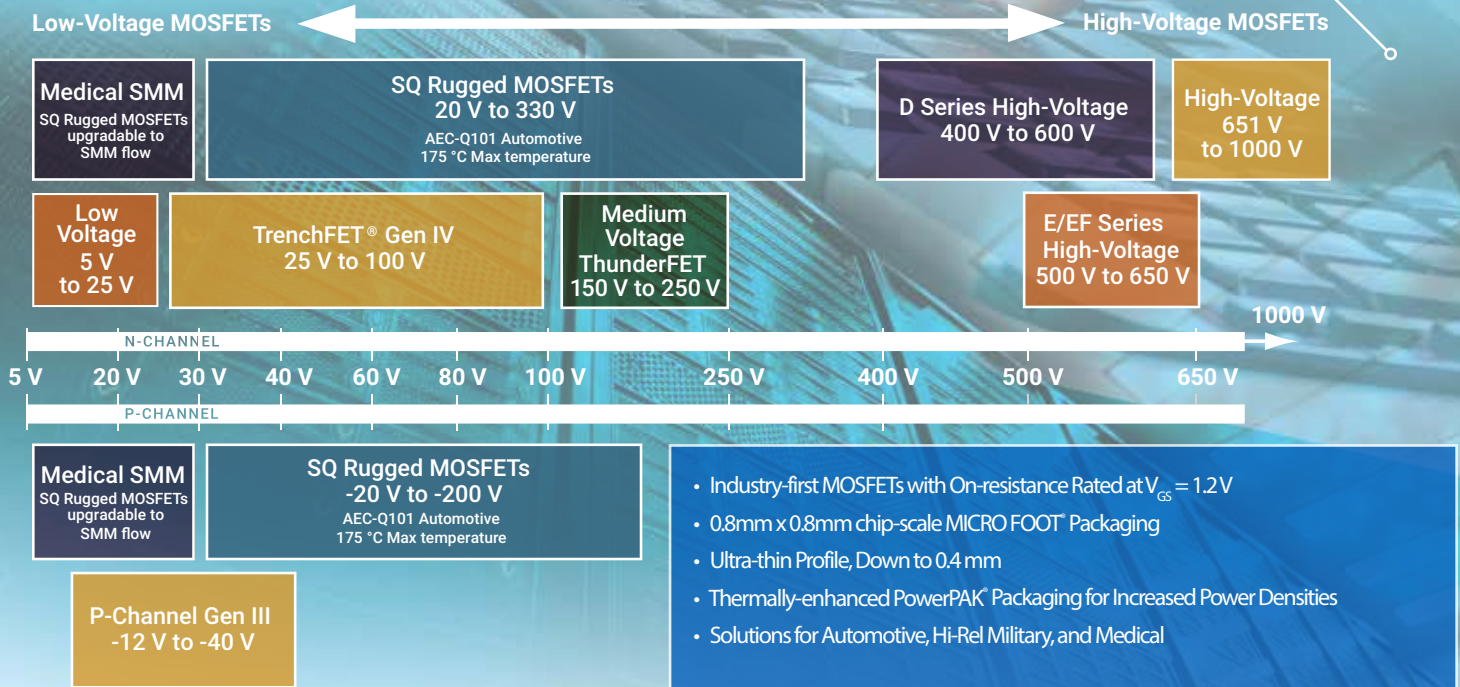




Vishay Power MOSFETs

Product Line Card



Vishay Siliconix power MOSFET product line combines state-of-the-art silicon design with innovative packaging to address your power management needs. Configuration options include single N and P devices in through-hole and surface-mount packages as well as dual N, P, and N&P in symmetric and asymmetric devices that optimize high- and low-side MOSFETs per application requirements. Vishay is your true one-stop shop for building blocks in power conversion applications providing high-performance MOSFETs ranging from +5 V to +1000 V for N-channel and -8 V to -400 V for P-channel in more than 30 package types.

Reach your local sales team at 1.800.CALL.TTI

Surface Mount Packages	Maximum HxWxD	Current Max (A)	$R_{\theta JF}$ or $R_{\theta JC}$ (°C/W)
TO-263-7L	15.88 x 10.41 x 4.83	200	0.4
D ² PAK (TO-263)	15.88 x 10.41 x 4.83	131	0.4
DPAK (TO-252)	10.41 x 6.73 x 2.38	50	1.2
PowerPAK 8x8L	8.1 x 8.25 x 1.9	200	1
PowerPAK 8x8	8.1 x 8.1 x 1.05	29	0.62
SOT-223	7.29 x 6.7 x 1.8	2.7	40
PowerPAIR® 6 x 5	6.08 x 5.08 x 0.8	60	1.25
PowerPAIR 6 x 3.7	6.08 x 3.81 x 0.8	35	2.6
PowerPAIR 3 x 3	3 x 3 x 0.8	40	4
PolarPAK®	6.3 x 5.31 x 0.85	60	1 + 1
PowerPAK® SO-8L	6.25 x 5.25 x 1.14	80	1.8
PowerPAK SO-8	6.2 x 5.26 x 1.2	100	1.2
SO-8	5 x 6.2 x 1.75	46	16
TSSOP-8	3.1 x 6.6 x 1.2	9.5	52
PowerPAK 1212-8	3.4 x 3.4 x 1.2	60	2.4
PowerPAK 1212-8S	3.3 x 3.3 x 0.83 31	50	2.2
Thin PowerPAK 1212-8T	3.4 x 3.4 x 0.8	50	2.4
TSOP-6	3.1 x 2.98 x 1.1	8	30
PowerPAK ChipFET®	3.08 x 1.98 x 0.85	25	4
1206-8 ChipFET	3.1 x 1.8 x 1.1	6	20
SOT-23	3.04 x 2.64 x 1.12	7.6	50
PowerPAK SC-70	2.15 x 2.15 x 0.8	37.8	6.5
Thin PowerPAK SC-70	2.15 x 2.15 x 0.65	12	6.5
SC-70	2.2 x 2.4 x 1.1	4	45
MICRO FOOT®	See Ind. Datasheet	16.7	20
PowerPAK SC-75	1.7 x 1.7 x 0.8	9	9.5
Thin PowerPAK SC-75	1.7 x 1.7 x 0.65	7.5	9.5
SC-75A	1.6 x 1.7 x 0.8	0.63	
SC-89	1.7 x 1.7 x 0.6	1.75	
PowerPAK 0806	0.85 x 0.65 x 0.4	1	

Through-Hole	Maximum HxWxD	Current Max (A)	$R_{\theta JF}$ or $R_{\theta JC}$ (°C/W)
Super 247 (RoHS only)	20.8 x 16.1 x 5.3	90	0.23
TO-247	20.7 x 15.87 x 5.31	100	0.3
TO-220 Full PAK	16.12 x 10.63 x 4.83	56.6	3
Thin-lead TO-220 FullPAK	15.3 x 10.3 x 4.7	56.6	3.6
TO-220	15.49 x 10.51 x 4.65	131	0.6
I ² PAK (TO-262)	11.3 x 10.67 x 4.83	50	0.8
HVMDIP	10.79 (L) x 5 x 3.37 (H)	2.4	120
IPAK (TO-251)	7.49 x 6.73 x 2.39	14	1.1



TrenchFET® Gen IV

Next-Generation Technology MOSFETs (30 V) for personal computers and peripherals, servers, VRMs, telecom equipment, POL, DC/DC modules, power redundancy, game consoles, DC/AC inverters, industrial



E Series and EF Series

High-Voltage MOSFETs (500 V, 600 V, and 650 V) for industrial, lighting, alternative energy applications, SMPS and battery chargers



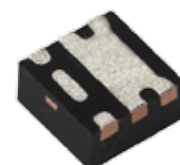
D Series

High-Voltage MOSFETs (400 V, 500 V, and 600V) for consumer electronics, industrial, lighting, battery charger, server, and telecom power supply applications



ThunderFET™ and Medium-Voltage MOSFETs

(40 V to 150 V) for industrial, telecom, solar, and motor control applications



P-Channel TrenchFET® Gen III

Industry Lowest On-Resistance for P-Channel MOSFETs (-12 V to -40 V) for industrial systems, portable devices and mobile computing applications



SQ Rugged Series

AEC-Q101 Automotive Qualified MOSFETs (20 V to 330 V n-ch and -12 V to -200 V p-ch) for engine controllers, transmission controllers, motor drives, lighting, body electronics, safety, and infotainment applications